

ABSTRACT

WIRE BONDING METHOD FOR FORMING LOW-LOOP PROFILES

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A method of forming a wire bond with a bonding tool is provided that comprises the steps of forming a ball bond onto a bonding surface, raising the bonding tool away from the ball bond to form a neck portion integrated with a top of the ball bond, locating a circumference of a tip of the bonding tool onto the neck portion, pressing the neck portion with the circumference of the tip to form a depression in the neck portion without bonding the neck portion to the ball bond, and thereafter raising the bonding tool away from the ball bond.

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(FIG. 4)

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